



Material Content Data Sheet



Sales Product Name				BSC093N04LS G		Issued		20. July 2018	
MA#				MA001299994					
Package				PG-TDSON-8-5		Weight*		123.58 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.804	0.65	0.65	6505	6505	
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		92		
	non noble metal	iron	7439-89-6	0.038	0.03		306		
	non noble metal	copper	7440-50-8	37.762	30.56	30.60	305558	305956	
	non noble metal	copper	7440-50-8	0.059	0.05	0.05	477	477	
wire	non noble metal	copper	7440-50-8	0.059	0.05	0.05	477	477	
encapsulation	organic material	carbon black	1333-86-4	0.097	0.08		785		
	plastics	epoxy resin	-	6.891	5.58		55758		
	inorganic material	silicondioxide	60676-86-0	41.538	33.60	39.26	336119	392662	
leadfinish	non noble metal	tin	7440-31-5	1.452	1.17	1.17	11746	11746	
plating	noble metal	silver	7440-22-4	0.166	0.13	0.13	1339	1339	
solder	non noble metal	tin	7440-31-5	0.022	0.02		180		
	noble metal	silver	7440-22-4	0.028	0.02		225		
	non noble metal	lead	7439-92-1	1.060	0.86	0.90	8578	8983	
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		28		
	non noble metal	iron	7439-89-6	0.011	0.01		92		
	non noble metal	copper	7440-50-8	11.320	9.16	9.17	91599	91719	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		54		
	non noble metal	iron	7439-89-6	0.022	0.02		181		
	non noble metal	copper	7440-50-8	22.292	18.04	18.07	180378	180613	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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